

Docket No.: 21581-00456-US
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Koji Watanabe et al.

Application No.: 10/541,586

Confirmation No.: 1996

Filed: September 30, 2005

Art Unit: 1712

For: CURING RESIN COMPOSITION, ADHESIVE
EPOXY RESIN PASTE, ADHESIVE APOXY
RESIN SHEET, CONDUCTIVE CONNECTION
PASTE, CONDUCTIVE CONNECTION
SHEET, AND ELECTRONIC COMPONENT
JOINED BODY

Examiner: M. J. Feely

RESPONSE UNDER 37 C.F.R. 1.111 (NON-FINAL OFFICE ACTION)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Madam:

INTRODUCTORY COMMENTS

This is in response to the Office Action mailed May 27, 2009 in the above-captioned case.

Amendments to the Claims are reflected in the Listing of Claims which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.